ABSTRACT

PACKAGING OF A MICROCHIP DEVICE

A method of packaging a microchip device, an interposer for packaging, and a packaged microchip device. An interposer (7) is placed on microchip devices (1). The interposer (7) comprises an aperture (11) which extends from the interposer surface where external electrical contacts (9) are located to the surface of the microchip devices (1). Electrical contacts (3) on the microchip device surface are accessible through the aperture (11) in order to electrically connect the electrical contacts (3) with the external electrical contacts (9) of the interposer (7). The interposer (7) comprises separate openings or aperture regions, in particular separated by a bridge (19), which extend from the interposer surface where the external contacts (9) are located into the interposer (7). This facilitates the handling of the finalised package and allows for satisfactory filling of the aperture (11) with filling material.

FIG. 5